

## **REMARKS**

Favorable reconsideration of this application is requested in view of the above amendments and the following remarks. Claim 1 is amended. Claims 29-31 are added. The revision to claim 1 is supported, for example, at Figure 15 and at page 36, line 19-25 in the specification. New claims 29-31 are supported, for example, at Figure 15 and page 40, line 15 through page 41, line 8 in the specification. Claims 1-11 and 28-31 are pending, with claim 1 being the sole independent claim.

### **Claim rejections - 35 U.S.C. § 103**

Claims 1, 2, 4-6, and 28 stand rejected as being unpatentable over U.S. Patent No. 4,876,451 (Ikeda). Applicant respectfully traverses this rejection.

Claim 1 is directed to a solid electrolytic capacitor. A base sheet member is brought into direct contact with a protection package between a first side surface and a second side surface of the protection package. The protection package is made only of a resin composition.

Ikeda does not teach or suggest at least these features. Ikeda is directed to a method of manufacturing solid electrolyte capacitors. However, the insulating base members disclosed in Ikeda (e.g., elements 67, 67', 76, and 76') are spaced apart from the protection package (e.g., elements 66 and 75). See, e.g., Figures 22-25. To the extent that the Examiner relies on the metallic case (e.g., elements 61 and 71) as being a part of a protection package, the metallic case is obviously not a resin composition.

Accordingly, Ikeda does not teach or suggest that a base sheet member is brought into direct contact with a resin protection package between a first side surface and a second side surface of the protection package.

Accordingly, Applicants respectfully submit that claim 1 is allowable over the cited reference. In addition, claims 2, 4-6, and 28 depend from claim 1, and are believed allowable for at least the same reasons.

Claims 1, 2, 4-9, 11, and 28 stand rejected as being unpatentable over Ikeda in combination with U.S. Patent No. 4,497,105 (Uemura). Applicant respectfully traverses this rejection.

Uemura does not remedy the deficiencies of Ikeda as noted above with respect to claim 1. For example, Applicant respectfully disagrees that it would be obvious to modify Uemura with

Ikeda by having a base sheet composed of a lamination layer 22 of Uemura with the insulation sheet 76' to obtain small-sized capacitors. In contrast, the use of two layers would cause the size of the device to increase. Moreover, the capacitor disclosed in Uemura is intended to be a self-contained device. See Figures 8 and 9. Therefore, there would be no motivation to include the insulation sheet 76' of Ikeda on the layer 22 of Uemura.

Accordingly, Applicant submits that claim 1 is allowable over the cited references. Claims 2, 4-9, 11, and 28 depend from claim 1 and are believed allowable for at least the same reasons.

Claim 3 stands rejected as being unpatentable over Ikeda in combination with Uemura and U.S. Patent No. 4,814,946 (Su). Claim 10 stands rejected as being unpatentable over Ikeda in combination with Uemura and U.S. Patent No. 5,390,074 (Hasegawa). Applicant respectfully traverses these rejections.

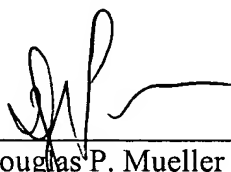
Claims 3 and 10 both depend from claim 1, which is believed allowable for the reasons stated above. Neither Su nor Hasegawa remedies the deficiencies of Ikeda and Uemura with respect to claim 1. Accordingly, Applicant submits that each of claims 3 and 10 is allowable over the cited references for at least the reason that it is dependent upon an allowable base claim. Applicant does not concede the correctness of these rejections.

In view of the above, favorable reconsideration in the form of a notice of allowance is requested.

Respectfully submitted,

MERCHANT & GOULD P.C.  
P.O. Box 2903  
Minneapolis, Minnesota 55402-0903  
(612) 332-5300

Date: June 10, 2004

  
\_\_\_\_\_  
Douglas P. Mueller  
Reg. No. 30,300  
DPM:DTL